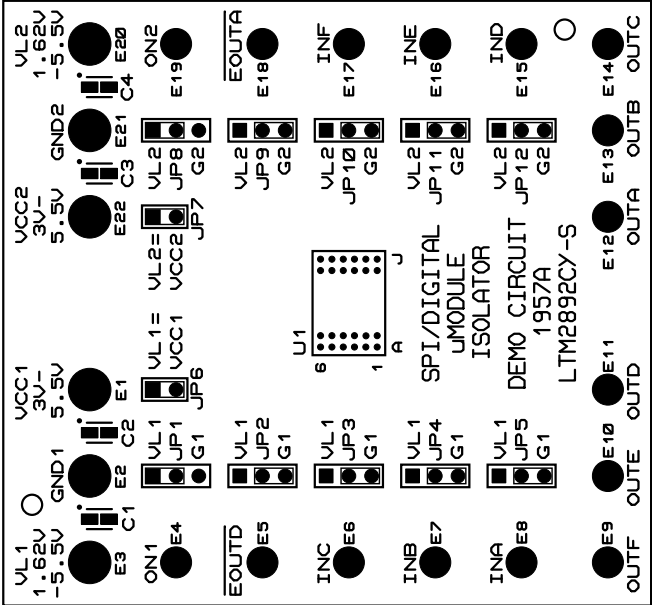


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPROVED	DATE
-	1	1ST PROTOTYPE	KEITH B.	4-17-12

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610
2. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS
3. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
5. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP AND BOTTOM SIDE SMD
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD
7. INSTALL SHUNTS AS SHOWN



APPROVALS		LTC CONFIDENTIAL FOR CUSTOMER USE ONLY	
PCB DES.	KEITH B.	1630 McCarthy Blvd. Milpitas, CA 95035 Phone: (408) 432-1900 Fax: (408) 434-0507 www.linear.com	
APP ENG.	KEITH B.		
SCALE = 1.5:1		TITLE: TOP ASSEMBLY DRAWING SPI/DIGITAL UMODULE ISOLATOR	
		SIZE	IC NO.
		N/A	LTM2892CY-S
			REV. 1
			1
DATE: Tuesday April 17, 2012		SHEET 1 OF 1	